CLAIMS

1. A method for detecting contaminants during a semiconductor fabrication operation involving a semiconductor coating device, said method comprising the steps of:

generating a beam of laser light from a said laser light source attached to at least one coater cup associated with said semiconductor coating device utilized in said semiconductor fabrication operation; and

automatically terminating said semiconductor fabrication operation, in response to detecting said contaminants utilizing said beam of laser light, wherein said contaminants are scattered as a result of said semiconductor fabrication operation.

- 2. The method of claim 1 further comprising the step of: detecting contaminants utilizing said beam of laser light.
- 3. The method of claim 1 further comprising the step of: attaching a laser light source to said at least one coater cup associated with said semiconductor coating device.

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- 4. The method of claim 1 wherein said coater cup comprises a photoresist (PR) cup.
- 5. The method of claim 1 wherein said laser light source comprises a laser generator.
- 6. The method of claim 1 wherein said laser light source comprises a laser detector.
- 7. The method of claim 1 wherein said laser light source comprises a laser generator integrated with a laser detector.
- 8. The method of claim 1 wherein said semiconductor fabrication operation comprises a wafer spin coating operation.
- 9. The method of claim 1 wherein said contaminant comprises dust.
- 10. The method of claim 1 wherein said contaminant comprises photoresist (PR) dust scattered as a result of a wafer spin coating operation.

flow.

11. The method of claim 1 further comprising the step of: detecting contaminants utilizing said beam of laser light, wherein said contaminants comprise an abnormal photoresist dust

12. The method of claim 1 further comprising the step of:

detecting contaminants utilizing at least one laser

detector to detect said beam of laser light generated from said

laser light source.

- 13. The method of claim 12 wherein said laser light source is generated by at least one laser generator.
- 14. The method of claim 1 wherein said at least one coater cup is configured from a transparent material.
- 15. The method of claim 14 wherein said transparent material comprises quartz.
- 16. The method of claim 14 wherein said transparent material comprises glass.

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17. A system for detecting contaminants during a semiconductor fabrication operation involving a semiconductor coating device, said system comprising:

a said laser light source attached to at least one coater cup associated with said semiconductor coating device utilized in said semiconductor fabrication operation, wherein said laser light source generates a beam of laser light;

a laser detector for detecting contaminants utilizing said beam of laser light, such that said contaminants are scattered as a result of said semiconductor fabrication operation; and

wherein said semiconductor fabrication operation is automatically terminated, in response to detecting said contaminants utilizing said beam of laser light.

- 18. The system of claim 17 wherein said coater cup comprises a photoresist (PR) cup.
- 19. The system of claim 17 wherein said laser light source comprises a laser generator.

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- 20. The system of claim 17 wherein said laser light source comprises a laser detector.
- 21. The system of claim 17 wherein said laser light source comprises a laser generator integrated with a laser detector.
- 22. The system of claim 17 wherein said semiconductor fabrication operation comprises a wafer spin coating operation.
- 23. The system of claim 17 wherein said contaminant comprises dust.
- 24. The system of claim 17 wherein said contaminant comprises photoresist (PR) dust scattered as a result of a wafer spin coating operation.
- 25. The system of claim 17 wherein said contaminants comprise an abnormal photoresist dust flow.

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- 26. The system of claim 17 wherein said contaminants are detectable utilizing at least one laser detector to detect said beam of laser light generated from said laser light source.
- 27. The system of claim 26 wherein said laser light source is generated by at least one laser generator.
- 28. The method of claim 17 wherein said at least one coater cup is configured from a transparent material.
- 29. The method of claim 28 wherein said transparent material comprises quartz.
- 30. The method of claim 28 wherein said transparent material comprises glass.